

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1-10 (cancelled).

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11 (currently amended): A chip-packaging with bonding options connected to a package substrate, comprising:

the package substrate connected to either a high voltage or a low voltage;

10 a chip mounted on the package substrate, the chip comprising a plurality of bonding option units, each bonding option unit comprising a bonding pad; and

a plurality of first lead frames, the bonding pad of each bonding option unit having a corresponding first lead frame such that there exists a one-to-one correspondence between the bonding pads and the first lead frames, the first lead frames being connected to either a high voltage or a low voltage, wherein the voltage level of the first lead frames is the logical opposite of the voltage level of the package substrate;

15 wherein the bonding pad of each bonding option unit is connected to the package substrate or the corresponding first lead frame for providing two types of bonding options for each bonding option unit.

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12-18 (cancelled).

19 (currently amended): A method of packaging a chip having a bonding option 25 connected to a package substrate, comprising:

providing the package substrate;

connecting the package substrate to either a high voltage or a low voltage;

mounting the chip on the package substrate, the chip comprising a plurality of bonding option units, each bonding option unit comprising a bonding pad; providing a plurality of first lead frames, the bonding pad of each bonding option unit having a corresponding first lead frame such that there exists a one-to-one correspondence between the bonding pads and the first lead frames, the first lead frames being connected to either a high voltage or a low voltage, wherein the voltage level of the first lead frames is the logical opposite of the voltage level of the package substrate; and connecting the bonding pad of each bonding option unit to the package substrate or the corresponding first lead frame for providing two types of bonding options for each bonding option unit.

20-32 (cancelled).

15 33 (currently amended): The chip-packaging of claim 11, further comprising a plurality of second lead frames, each bonding pad of the chip having a corresponding second lead frame such that there exists a one-to-one correspondence between the bonding pads and the second lead frames, wherein the second lead frames are used for inputting or outputting signals to the corresponding bonding pad, and each bonding pad is connected to the package substrate, the corresponding first lead frame, or the corresponding second lead frame for providing three types of bonding options for each bonding option unit.

20 34 (currently amended): The method of claim 19, further comprising providing a plurality of second lead frames, each bonding pad of the chip having a corresponding second lead frame such that there exists a one-to-one correspondence between the bonding pads and the second lead frames, wherein the second lead frames are used for inputting or outputting signals to the corresponding bonding pad,

and each bonding pad is connected to the package substrate, the corresponding first lead frame, or the corresponding second lead frame for providing three types of bonding options for each bonding option unit.

5 35 (new): A chip-packaging with bonding options connected to a package substrate, comprising:
the package substrate connected to either a high voltage or a low voltage;
a chip mounted on the package substrate, the chip comprising a plurality of bonding option units, each bonding option unit comprising a bonding pad;
10 and
a plurality of first lead frames, each bonding pad of the chip having a corresponding first lead frame, the first lead frames being connected to a voltage logically opposite of the voltage level of the package substrate;
wherein each bonding pad is connected to one of the package substrate and the
15 corresponding first lead frame with the other of the package substrate and the corresponding lead frame remaining unconnected, thereby providing two types of bonding options for each bonding pad.

36 (new): A method of packaging two identical chips to two different ICs, comprising:
20 providing two identical package substrates respectively for the two chips;
respectively mounting each chip on its respective package substrate, each chip comprising a plurality of bonding option units, each bonding option unit comprising a bonding pad;
providing a plurality of first lead frames for each package substrate, each
25 bonding pad of each chip having a corresponding first lead frame;
for a said chip, connecting at least one predetermined bonding pad of the said bonding pads to the corresponding package substrate; and
for the other said chip, connecting at least one bonding pad equivalent to the

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said at least one predetermined bonding pads to corresponding first lead frame of the corresponding package substrate such that identical chips are packaged to different ICs.